

General Description

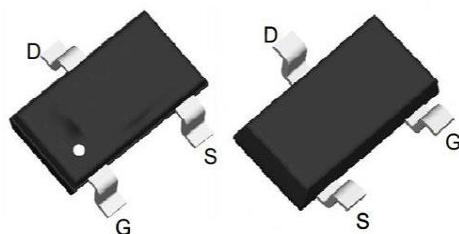
30V /5A Single N Power MOSFET

Very low on-resistance RDS(on) @ VGS=4.5 V

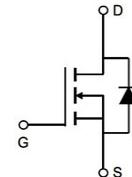
Pb-free lead plating; RoHS compliant

| | | |
|---------------------------------------|------|----|
| V_{DS} | 30 | V |
| R_{DS(on),TYP@VGS=10V} | 30.1 | mΩ |
| R_{DS(on),TYP@VGS=4.5} | 47.3 | mΩ |
| I_D | 5 | A |

Top View



Bottom View



| Part ID | Package Type | Marking | Tape and reel infomation |
|---------|--------------|---------|--------------------------|
| AC3404 | SOT23-3 | 3404 | 3000 |

100% UIS Tested
100% RG Tested

| Parameter | Symbol | Maximum | Units |
|--|-----------------------------------|------------|-------|
| Drain-Source Voltage | V _{DS} | 30 | V |
| Gate-Source Voltage | V _{GS} | 20 | ±V |
| Continuous Drain Current A | I _D | 5.0 | A |
| | | 4.0 | |
| Pulsed Drain Current B | I _{DM} | 8.0 | A |
| Avalanche Current G | I _{AR} | 1.6 | |
| Repetitive avalanche energy L=0.1mH G | E _{AR} | 3.7 | mJ |
| Power Dissipation A | P _D | 1.4 | W |
| | | 0.9 | |
| Junction and Storage Temperature Range | T _J , T _{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|-------------------------------|------------------|-----|-----|-------|
| Maximum Junction-to-Ambient A | R _{θJA} | 107 | 161 | °C/W |
| Maximum Junction-to-Ambient A | | 215 | 258 | °C/W |
| Maximum Junction-to-Lead c | R _{θJL} | 64 | 103 | °C/W |

STATIC PARAMETERS

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--------------|---------------------------------------|-----------------------------------|-----|------|-----------|-----------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D = -250\mu A, V_{GS} = 0V$ | 30 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=30V, V_{GS}=0V$ | | | 1 | uA |
| | | | | | 5 | |
| I_{GSS} | Gate-Body leakage current | $V_{DS} = 0V, V_{GS} = \pm 20V$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1.2 | 1.8 | 2.4 | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=-10V, I_D=5A$ | | 30.1 | 43.0 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=5A$ | | 47.3 | 61.5 | |
| g_{FS} | Forward Transconductance | $V_{DS}=5V, I_D=5A$ | | 80 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=1A, V_{GS}=15V$ | | 0.72 | 1 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 5 | A |

DYNAMIC PARAMETERS

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------|------------------------------|---------------------------------|-----|-----|------|----------|
| C_{iss} | Input Capacitance | $V_{GS}=0V, V_{DS}=15V, f=1MHz$ | | 255 | 311 | pF |
| C_{oss} | Output Capacitance | | | 45 | 55 | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 35 | 41 | pF |
| R_g | Gate resistance | $V_{GS}=0V, V_{DS}=0V, f=1MHz$ | | | 0.65 | Ω |

SWITCHING PARAMETERS

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--------------|------------------------------------|--|-----|-------|-----|-------|
| $Q_g(10V)$ | Total Gate Charge | $V_{GS}=10V, V_{DS}=15V, I_D=5A$ | | 2.55 | | nC |
| $Q_g 4.5V)$ | Total Gate Charge | | | 1.275 | | |
| Q_{gs} | Gate Source Charge | | | 0.91 | | |
| Q_{gd} | Gate Drain Charge | | | 1.3 | | |
| $t_{D(on)}$ | Turn-On DelayTime | $V_{GS}=10V, V_{DS}=15V, RL=0.75\Omega, R_{GEN}=3\Omega$ | | 4.25 | | ns |
| t_r | Turn-On Rise Time | | | 3.4 | | |
| $t_{D(off)}$ | Turn-Off DelayTime | | | 11.9 | | |
| t_f | Turn-Off Fall Time | | | 3.825 | | |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=-8A, dI/dt=500A/\mu s$ | | 8.5 | | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=18A, dI/dt=500A/\mu s$ | | 2.2 | | nC |

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

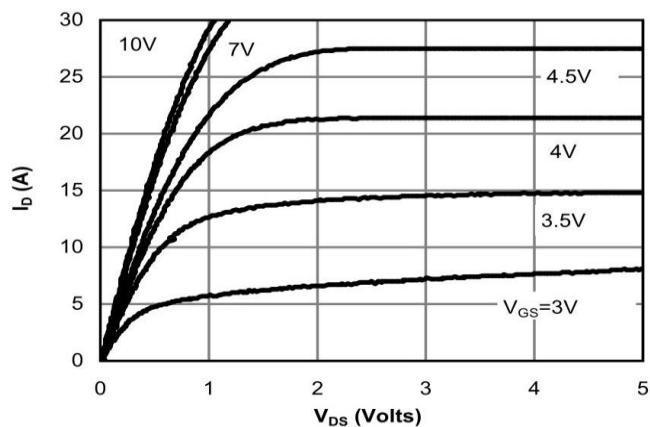


Fig 1: On-Region Characteristics (Note E)

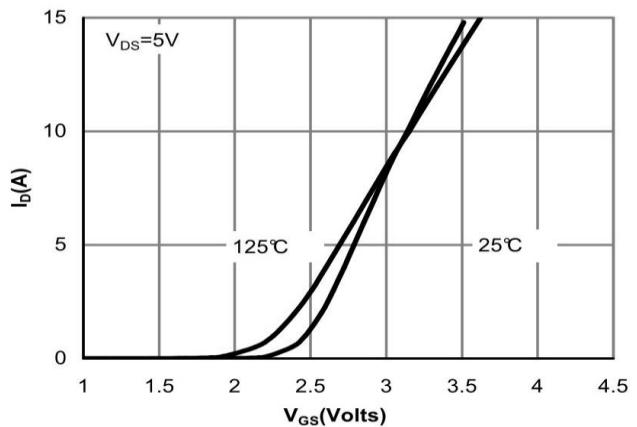


Figure 2: Transfer Characteristics (Note E)

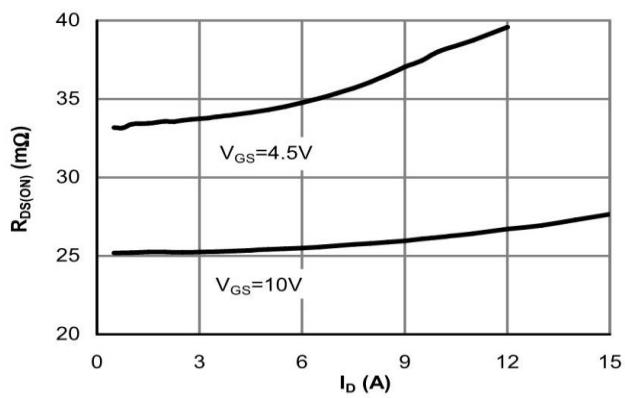


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

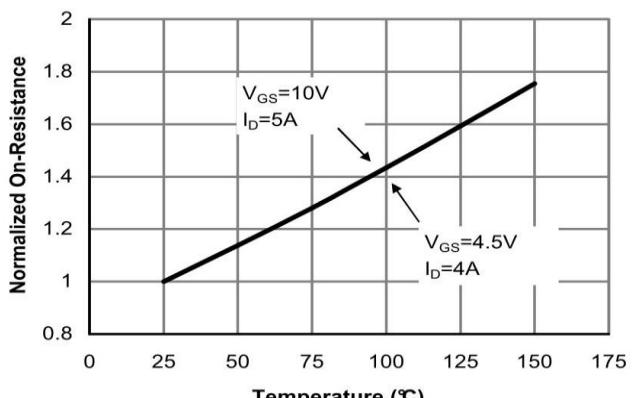


Figure 4: On-Resistance vs. Junction Temperature (Note E)

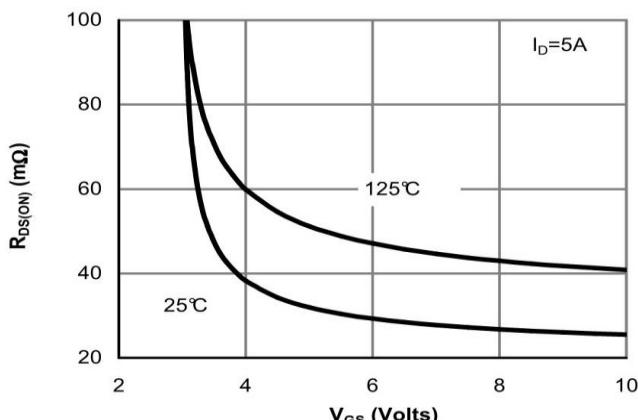


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

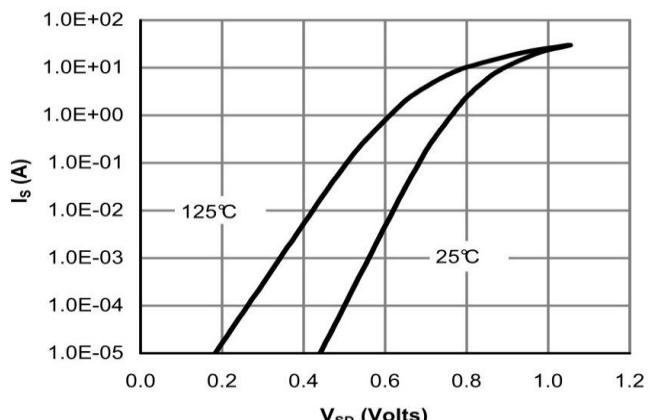


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

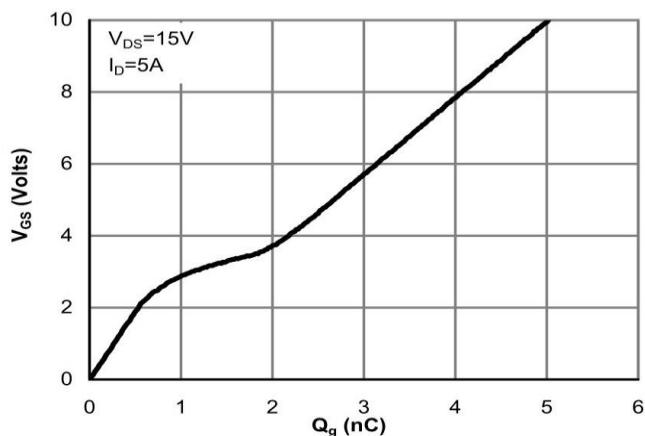


Figure 7: Gate-Charge Characteristics

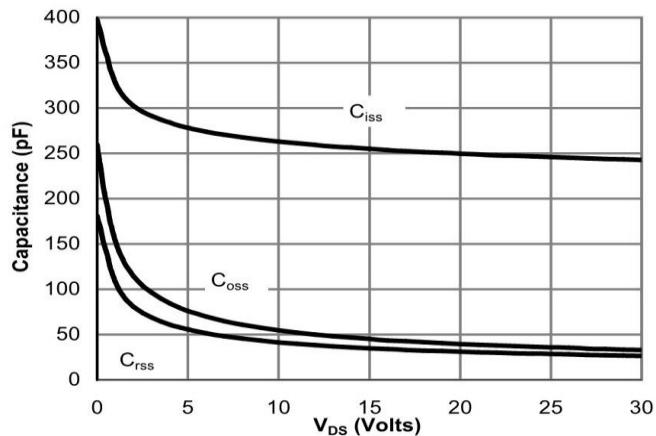


Figure 8: Capacitance Characteristics

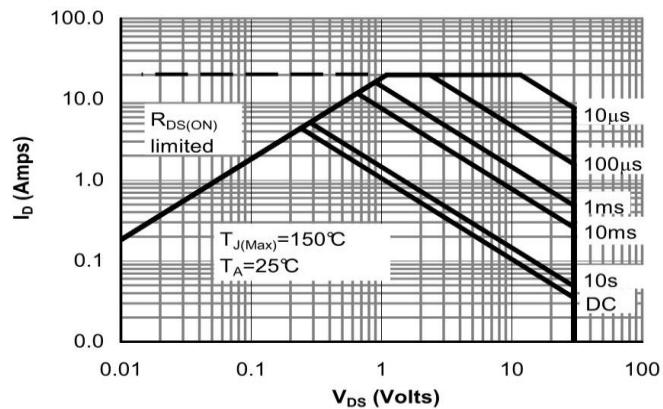


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

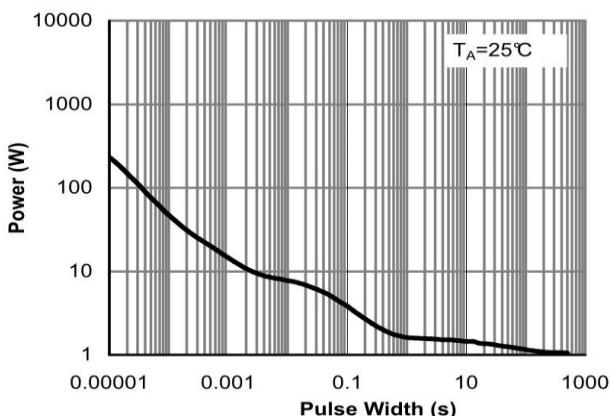


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

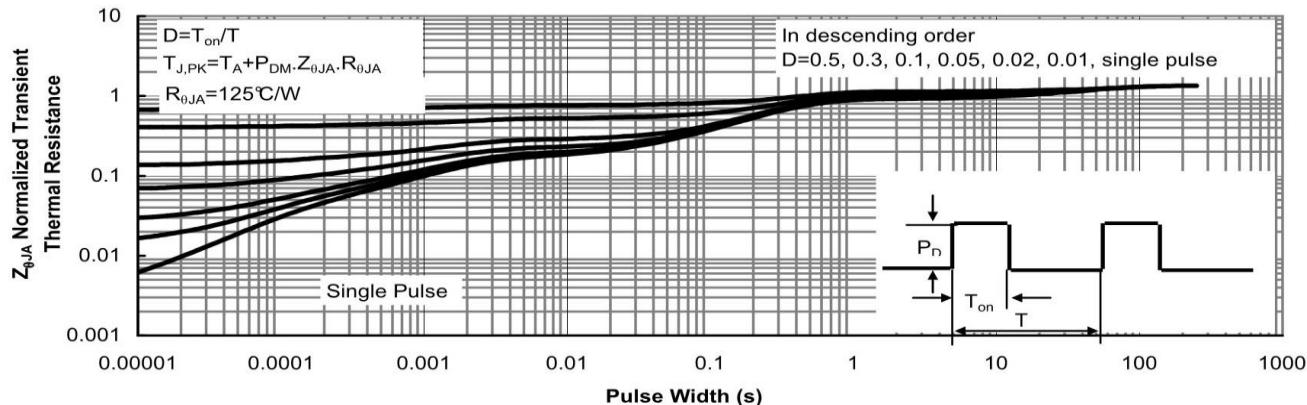


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)